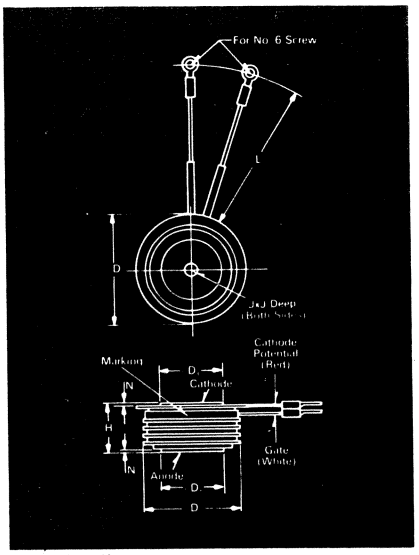
Fast Switching SCR T9GH_ _08

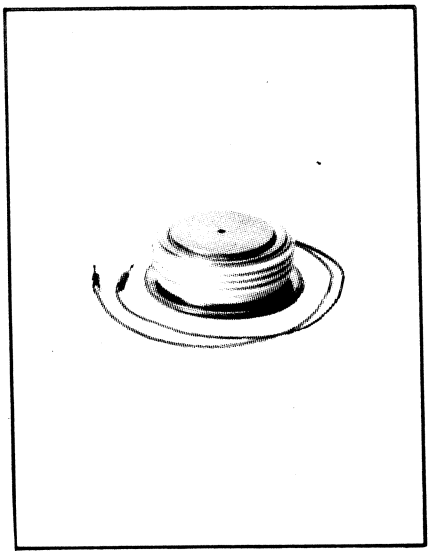
800A Avg. (1250 RMS) Up to 2000 Volts 50-100 μs



T9G Outline

Symbol	Inches		Millimeters	
	Min.	Max.	Min.	Max.
φD	2.850	2.900	72.39	73.66
ϕD_1	1.845	1.855	46.86	47.12
ϕD_2	2.560	2.640	65.02	67.06
H	1.030	1.070	26.16	27.18
φJ	.135	.145	3.43	3.68
J_1	.075	.090	1.91	2.29
L	11.50	12.50	292.10	317.50
N	.050		1.27	

Creep Distance—1.20 in. min. (30.48 mm).
Strike Distance—.07 in. min. (17.78 mm).
(In accordance with NEMA standards.)
Finish—Nickel Plate.
Approx. Weight—2 lb. (908 g).
1. Dimension "H" is a clamped dimension.



Features:
- Midway, di/namic Gate Structure
- Hard Commutation Turn-Off
- Forward Blocking Capabilities to 2000
- Low Switching Losses at High Frequency
- Soft Commutation (Feedback Diode) Testing Available

Applications:
- Induction Heating
- Transportation
- Inverters
- Crowbars

Ordering Information

Type	Voltage		Current		Turn-off		Gate current		Leads	
Code	V_{DRM} and V_{RRM} * (V)	Code	$I_{T(av)}$ (A)	Code	tq usec	Code	I_{GT} (ma)	Code	Case	Code
T9GH	600	06	800	08	50	3	300	2	T9G	DH
	800	08			60	2				
	1000	10			70	C				
	1200	12			80	I				
	1400	14			100	K				
	1500	15								
	1600	16								
	1700	17								
	1800	18								
	2000	20								

Example

Obtain optimum device performance for your application by selecting proper order code.

Type T9GH rated at 800A average with V_{DRM} = 1800V
tq = 60 usec.
I_{GT} = 300 ma, and standard 12 inch leads -- order as:

Type				Voltage		Current		Turn Off	Gate Current	Leads	
T	9	G	H	1	8	0	8	3	2	D	H

*for lower voltages consult factory

800A Avg. (1250 RMS) Up to 2000 Volts 50-100 μs

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Voltage

Blocking State Maximums ② (T_J = 125°C)

	Symbol	T9GH_ _08									
Repetitive peak forward blocking voltage, V	V_{DRM}	600	800	1000	1200	1400	1500	1600	1700	1800	1900	2000
Repetitive peak reverse voltage, V	V_{RRM}	600	800	1000	1200	1400	1500	1600	1700	1800	1900	2000
Non-repetitive transient peak reverse voltage, t ≤ 5.0 msec, V	V_{RSM}	700	900	1100	1300	1500	1600	1700	1800	1900	2000	2100
Forward leakage current, mA peak	I_{DRM}	60										
Reverse leakage current, mA peak	I_{RRM}	60										

Current

Conducting State Maximums (T_J = 125°C)	Symbol	T9GH_ _08
RMS forward current, A	$I_{T(rms)}$	1250
Ave. forward current, A	$I_{T(av)}$	800
One-half cycle surge current③, A	I_{TSM}	10,000
3 cycle surge current③, A	I_{TSM}	7,500
10 cycle surge current③, A	I_{TSM}	6,200
I^2t for fusing (t=8.3 ms) A^2sec	I^2t	416,000
Max I^2t of package (t=8.3 ms), A^2sec	I^2t	90 x 10^6
Forward voltage drop at I_{TM} = 1500A and T_J = 25°C, V	V_{TM}	2.5
Min. Repetitive di/dt A/usec. ① ④ ⑤ di/dt		500

Gate

(T_J=25°C)	Symbol	Min	Typ	Max
Gate current to trigger at V_D=12V, mA	I_{GT}		200	300
Gate voltage to trigger at V_D=12V, V	V_{GT}		1.5	3.0
Non-triggering gate voltage, T_J=125°C, and rated V_{DRM}, V	V_{GDM}			.15
Non-triggering Gate Current at V_D=12V, mA	I_{GNT}		20	
Peak forward gate current, A	I_{GTM}			10
Peak reverse gate voltage, V	V_{GRM}			5
Peak gate power, Watts	P_{GM}			60
Average gate power, Watts	$P_{G(av)}$			3

Switching

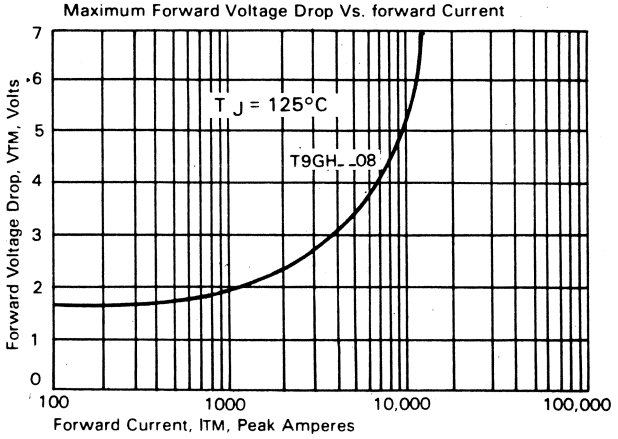
(T_J=25°C)	Symbol	
HARD COMMUTATION: ①		
Maximum Turn-off time, I_T = 1000A 50V≤V_R≤V_{RRM} T_J = 125°C, di $_R$/dt = 100A/usec reapplied dv/dt = 200V/usec linear to 0.8 V_{DRM}, usec	tq	50-100
Typical Turn-On and Delay Time I_{TM} = 1000A, tp = 450④ usec	ton	3.0
V_D = 1100V, usec	td	1.5
Minimum Critical dv/dt exponential to V_{DRM} T_J = 125°C, V/usec ② ⑤	dv/dt	400
Minimum di/dt @ non-repetitive, ① ④ ⑤ A/usec	di/dt	1000
Latching Current V_D = 75V, mA	Typ I_L	500
Holding Current	Max I_L	1000
V_D = 75V, ma	Typ I_H	300
	Max I_H	800

Thermal and Mechanical

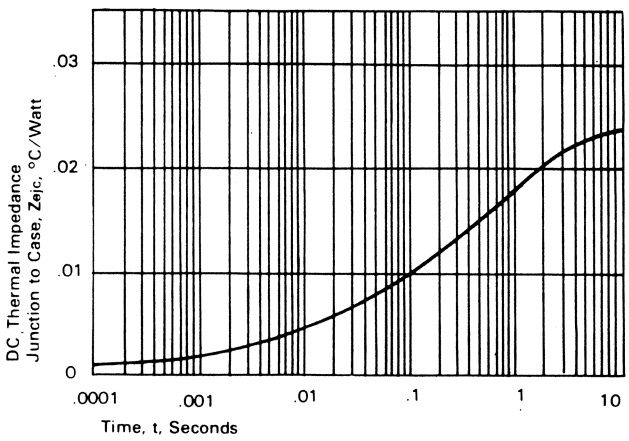
	Symbol	Min	Typ	Max
Oper. junction temp., °C	T_J	—40		125
Storage temp., °C	T_{stg}	—40		150
Mounting force, lb.⑪		5000		5500
Thermal resistance with double sided cooling⑪ Junction to case, °C/Watt	R⑪JC			.023
Case to sink, lubricated, °C/Watt	R⑪CS	.006		.0075

① Consult recommended mounting procedures.
② Applies for zero or negative gate bias.
③ Per JEDEC RS-397, 5.2.2.1.
④ With recommended gate drive.
⑤ Higher dv/dt ratings available, consult factory.
⑥ Per JEDEC standard RS-397, 5.2.2.6.
⑦ For operation with antiparallel diode, consult factory.

Maximum Forward Voltage Drop Vs. forward Current



Transient Thermal Impedance VS. Time

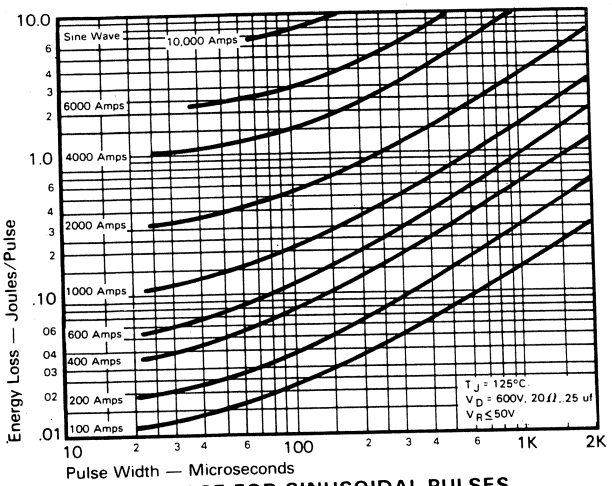


FAST SWITCHING THYRISTORS

Fast Switching SCR T9GH_ _08

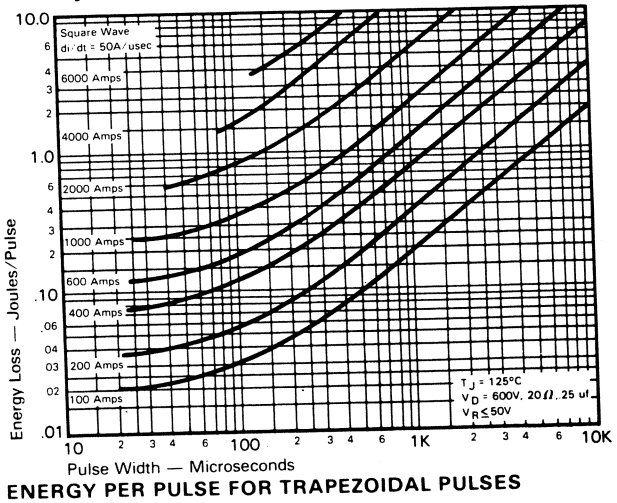
800A Avg. (1250 RMS) Up to 2000 Volts 50-100 μs

Sinusoidal Current Data

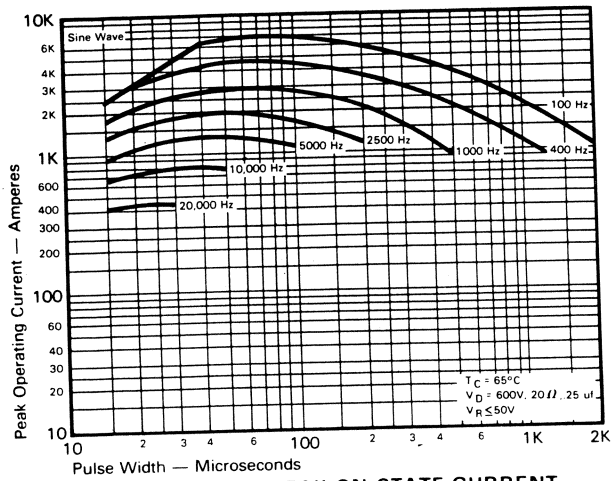


ENERGY PER PULSE FOR SINUSOIDAL PULSES

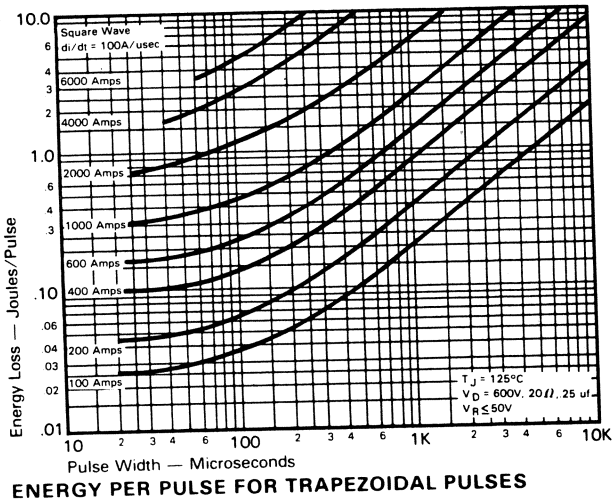
Trapezoidal Wave Current Data



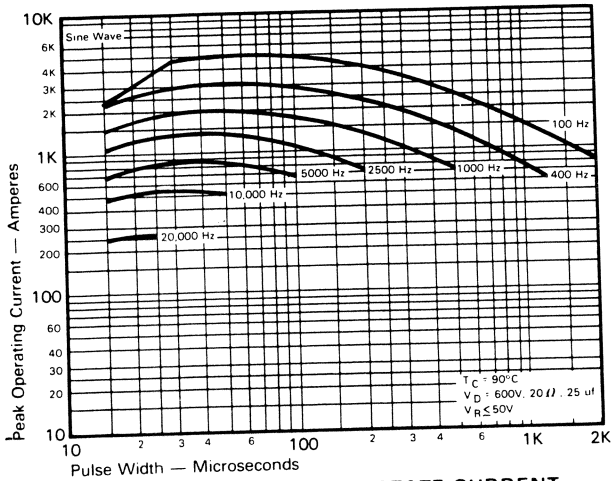
ENERGY PER PULSE FOR TRAPEZOIDAL PULSES (di/dt = 50A/usec)



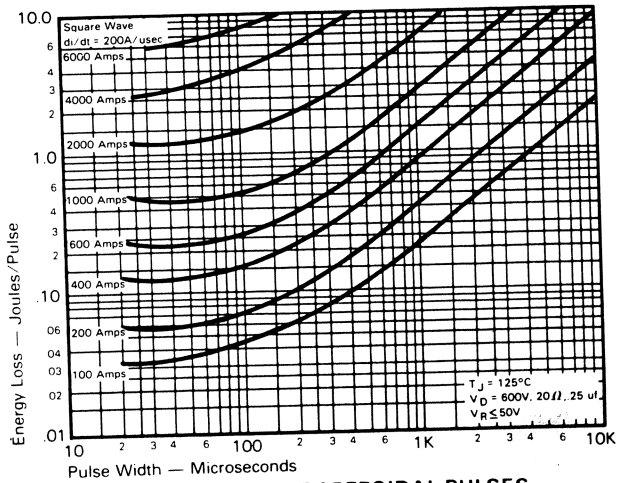
MAXIMUM ALLOWABLE PEAK ON-STATE CURRENT vs. PULSE WIDTH (T_C = 65°C)



ENERGY PER PULSE FOR TRAPEZOIDAL PULSES (di/dt = 100A/usec)



MAXIMUM ALLOWABLE PEAK ON-STATE CURRENT vs. PULSE WIDTH (T_C = 90°C)



ENERGY PER PULSE FOR TRAPEZOIDAL PULSES (di/dt = 200A/usec)

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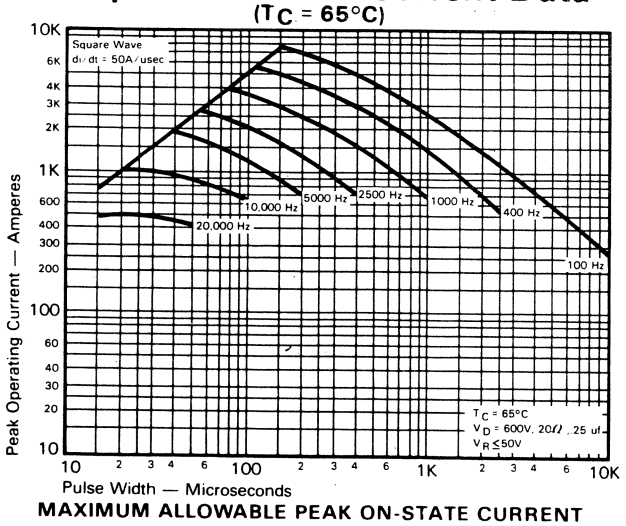
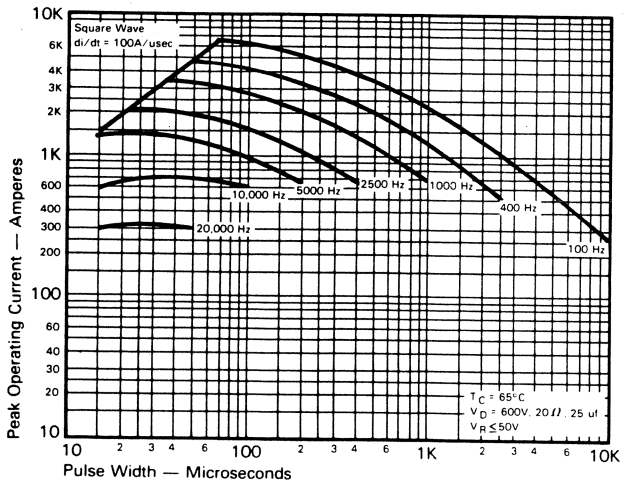
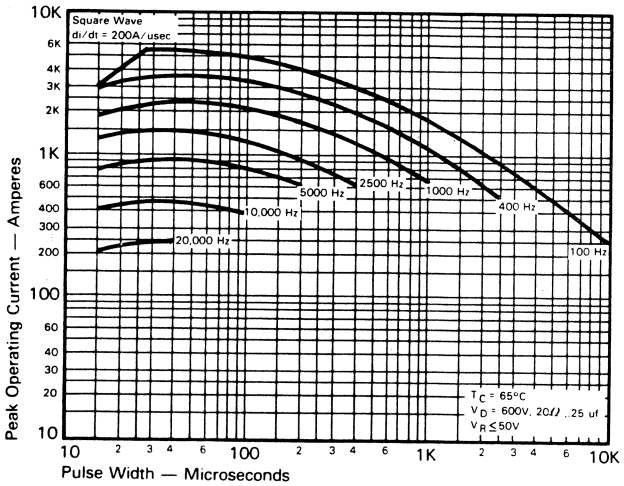
Trapezoidal Wave Current Data (T_C = 65°C)



MAXIMUM ALLOWABLE PEAK ON-STATE CURRENT vs. PULSE WIDTH (di/dt = 50A/usec)

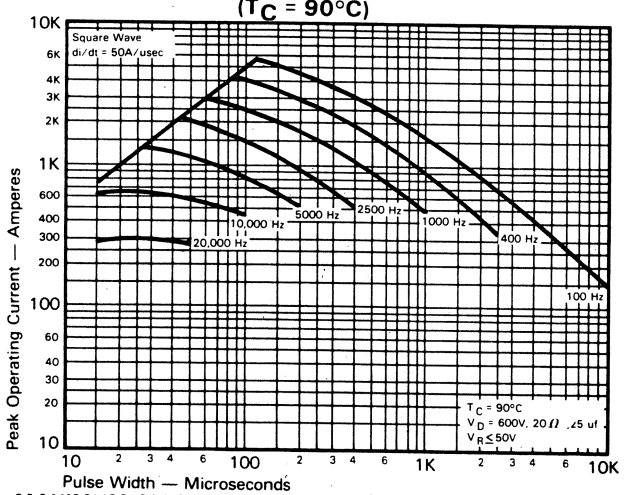


MAXIMUM ALLOWABLE PEAK ON-STATE CURRENT vs. PULSE WIDTH (di/dt = 100A/usec)

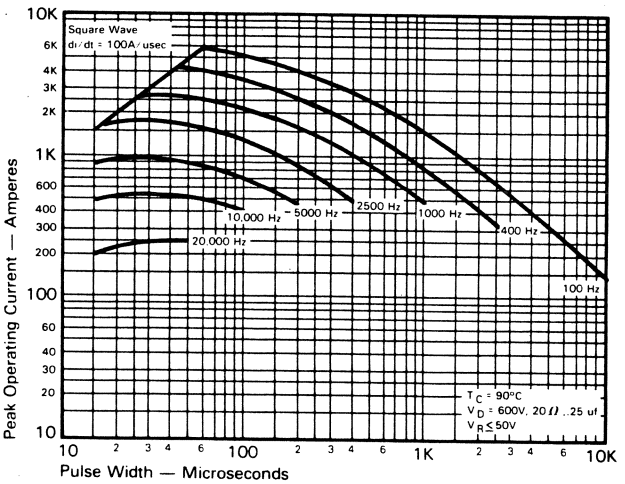


MAXIMUM ALLOWABLE PEAK ON-STATE CURRENT vs. PULSE WIDTH (di/dt = 200A/usec)

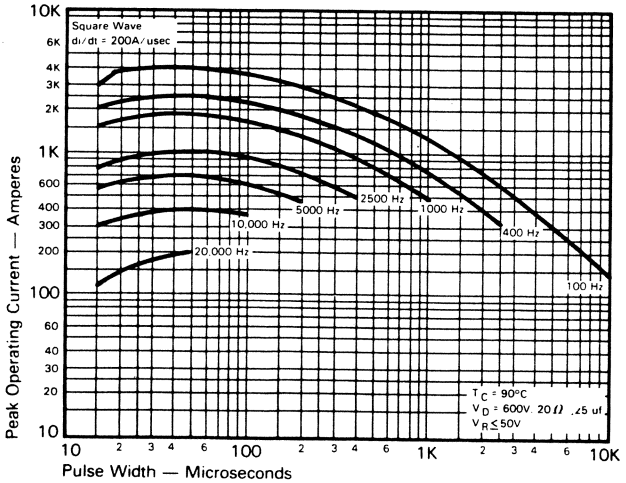
Trapezoidal Wave Current Data (T_C = 90°C)



MAXIMUM ALLOWABLE PEAK ON-STATE CURRENT vs. PULSE WIDTH (di/dt = 50A/usec)



MAXIMUM ALLOWABLE PEAK ON-STATE CURRENT vs. PULSE WIDTH (di/dt = 100A/usec)



MAXIMUM ALLOWABLE PEAK ON-STATE CURRENT vs. PULSE WIDTH (di/dt = 200A/usec)